

### REMARKS

Claim 5 currently remains in the application. Claims 1-3 and 6-9 have been canceled, claim 4 has been withdrawn and claim 5 is herein amended.

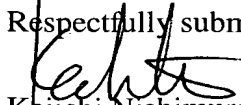
Claim 5 was rejected firstly under 35 U.S.C. 112. A definite article was replaced by an indefinite article in response to the rejection. It is therefore believed that the rejection has been obviated.

Claim 5 was rejected secondly under 35 U.S. C. 103 over Holmstrand or Minami in view of Japanese reference 4111114808 (hereinafter referred to as "Ohno"). In view of these cited references and the Examiner's reasons for rejection, claim 5 is herein amended by limiting the lapping plate as having a flat and smooth surface with a diameter greater than that of the target object and the mother particles as comprising spherical polymers. These additional limitations are supported by the specification and hence believed to be enterable.

These additional limitations are further believed to obviate the Examiner's rejection on the obviousness ground. Holmstrand's method is characterized as using a lapping plate having a surface embedded with abrading particles (column 4, lines 53-56) and hence not smooth. Minami's method is characterized as using a pair of ring-shaped lapping plates no larger than the wafer diameter to simultaneously polish both surfaces of the wafer (Abstract). Thus, although a slurry as described by Ohno is used in a method according to Holmstrand or Minami, there does not result a method according to claim 5 of the present application.

By the method of claim 5 according to the present invention, a slurry with elastic mother particles of spherical polymers and abrading particles dispersed therein is supplied such that these mother particles function like a pad during the polishing process. None of the cited references includes any statement that would suggest this essential feature of claim 5 and hence it is believed that claim 5 is not obvious and hence allowable even if all of the cited references are considered in combination.

Respectfully submitted,



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